



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Sakae KOYATA et al.

Group Art Unit : Not Yet Assigned

Appl. No. : 10/596,177

Examiner : Not Yet Assigned

(National Stage of PCT/JP2004/018067)

I.A. Filed : December 3, 2004

Confirmation No. : 3188

For : METHOD FOR MANUFACTURING SINGLE-SIDE
MIRROR SURFACE WAFER

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop AMENDMENT
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and §§1.97-1.98,
Applicants hereby bring to the attention of the Examiner the following information.

The following documents were cited in an International Search Report with
respect to International Patent Application No. PCT/JP2004/018067, of which the
present application is the U.S. National Stage Application. Copies of the International
Search Report (in Japanese and English) have been filed concurrently with the present
application and should thus have already been brought to the attention of the Examiner.

- (1) Japanese Laid-Open Patent Publication No. 2002-203823, along with
patent family member U.S. Patent Application Publication No.

2003/0171075 to NIHONMATSU et al., which was published on September 11, 2003;

- (2) Japanese Laid-Open Patent Publication No. 2003-077875, together with an English language Abstract and an English language computer translation thereof;
- (3) Japanese Laid-Open Patent Publication No. HEI 10-092777, along with patent family member U.S. Patent No. 5,899,731 to KAI et al., which issued on May 4, 1999;
- (4) Japanese Laid-Open Patent Publication No. 2003-203890, together with an English language Abstract and an English language computer translation thereof;
- (5) Japanese Laid-Open Patent Publication No. HEI 10-135165, along with patent family member U.S. Patent No. 6,043,156 to KAI et al., which issued on March 28, 2000;
- (6) Japanese Laid-Open Patent Publication No. HEI 10-135164, along with patent family member U.S. Patent No. 5,963,821 to KAI et al., which issued on October 5, 1999;
- (7) Japanese Laid-Open Patent Publication No. 2003-100701, together with an English language Abstract and an English language computer translation thereof; and
- (8) Japanese Laid-Open Patent Publication No. 2002-025950, along with patent family member U.S. Patent Application Publication No.

2003/0104698 to TANIGUCHI et al., which was published on June 5, 2003. Applicants note that the Japanese document is cited beginning page 3 of the specification of the above-captioned application.

The relevance of the documents cited in the International Search Report, as ascertained with respect to the international claims by the International Examiner, are set forth in the International Search Report.

Further to 37 C.F.R. §1.98 (a)(2)(ii), copies of the U.S. patents and patent application publications are not enclosed herewith. However, if any copy is needed, the Examiner is respectfully requested to contact the undersigned.

Applicants respectfully request that the Examiner consider the above material and cite the same. Copies of the above-noted foreign documents, including the noted English language Abstracts and translations, are attached hereto, and all of the documents are listed on an attached PTO-1449 Form. The Examiner is requested to initial the appropriate spaces on the attached Form and to return a copy of the completed Form to Applicants with the next official communication in the present application.

Applicants note that an Office Action on the merits has not issued in the present application, and thus, no fee is believed necessary to ensure consideration of the submitted material.


The undersigned notes that the present Information Disclosure Statement is being submitted prior to the mailing of an Action based upon the merits. Thus, no fee is required to be paid to ensure consideration of the documents cited therein. However,

should this Information Disclosure Statement cross in the mail with an Action based upon the merits, the Examiner is authorized to charge Deposit No. 19-0089 the appropriate fee to ensure consideration of the cited materials.

Should the Examiner have any questions, the Examiner is invited to contact the undersigned at the below-listed telephone number.

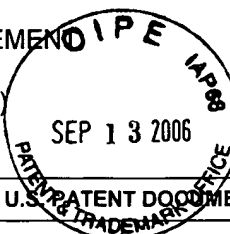
Respectfully submitted,
Noriyuki TAJIMA et al.

William S. Boshnick
Reg. No. 44,550


Bruce H. Bernstein
Reg. No. 29,027

September 12, 2006
GREENBLUM & BERNSTEIN, P.L.C.
1950 Roland Clarke Place
Reston, Virginia 20191
(703) 716-1191

FORM PTO-1449		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. P30044		Application No. 10/596,177	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)				Applicant Sakae KOYATA et al.			
Filing Date I.A. Filed December 3, 2004				Group Not Yet Assigned			



U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	2003 /	0 1 7 1 0 7 5	09/11/03	NIHONMATSU et al.			
		5 8 9 9 7 3 1	05/04/99	KAI et al.			
		6 0 4 3 1 5 6	03/28/00	KAI et al.			
		5 9 6 3 8 2 1	10/05/99	KAI et al.			
	2003 /	0 1 0 4 6 9 8	06/05/03	TANIGUCHI et al.			

FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
	2002	- 2 0 3 8 2 3	07/19/02	JAPAN				
	2003	- 0 7 7 8 7 5	03/14/03	JAPAN			X	
	10	- 0 9 2 7 7 7	04/10/98	JAPAN				
	2003	- 2 0 3 8 9 0	07/18/03	JAPAN			X	
	10	- 1 3 5 1 6 5	05/22/98	JAPAN				
	10	- 1 3 5 1 6 4	05/22/98	JAPAN				
	2003	- 1 0 0 7 0 1	04/04/03	JAPAN			X	
	2002	- 0 2 5 9 5 0	01/25/02	JAPAN				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)	
	English Language Abstract of JP 2003-077875.
	English Language Abstract of JP 2003-203890.
	English Language Abstract of JP 2003-100701.

EXAMINER	DATE CONSIDERED
----------	-----------------

*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.